

THIN-FILM RESISTOR AND METHOD OF MANUFACTURING THE SAME

Abstract

The invention relates to integration of a thin-film resistor in a wiring level, such as, for example, an aluminum back-end-of-line (BEOL) technology. The thin-film resistor is formed in a wiring level on, for example, an upper surface of a dielectric layer. The thin-film resistor includes end portions tapered at an angle less than 90 degrees with respect to the upper surface. The tapered end portions provide increased surface area for making contact to the thin-film resistor without adversely affecting the resistance value of the thin-film resistor.